

<b>ENGINEERING</b> <b>DEPT.</b>	<b>PRODUCT SPECIFICATION</b> <b>For 2.00 mm (.079") Pin Header of System CH71</b>	<b>SPEC.NO.: SPCH020B</b> <b>PAGE: 1/4</b>
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1. SCOPE:

This specification contains the test requirement of subject pin headers when tested under the condition and below standards base on CviLux test procedure

2. APPLICABLE STANDARDS:

MIL - STD - 202	Methods for test of connectors for electronic equipment
MIL - STD - 1344	Test methods for electrical connectors
JIS - C - 5402	Methods for test of connectors for electronic equipment
UL 94	Test for flammability of plastic materials for parts in devices and appliance

3. APPLICABLE SERIES NO.: **CH71 SERIES**

4. SHAPE, CONSTRUCTION AND DIMENSIONS

See attached drawings

5. MATERIALS

See attached drawings

6. ACCOMMODATED P.C.BOARD

(P.C. Board on which the Pin Header are installed), 0.8 mm (.031") ~ 1.6 mm (.063")



REVIEWED :  Alex  APPROVED :  David  VERIFIED :  Sun  .

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**7. ELECTRICAL PERFORMANCE:**

	ITEM	TEST CONDITION	
7.1	Rated current and voltage		1A 250V AC (r.m.s.)
7.2	Contact resistance	Dry circuit of DC 20 mV max. , 100 mA max.	Less than 20 mΩ
7.3	Dielectric strength	When applied AC 1000 V 1minute between adjacent terminal	No change
7.4	Insulation resistance	When applied DC 500 V between adjacent terminal or ground	More than 1000 MΩ

**8. MECHANICAL PERFORMANCE:**

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Pin retention force	Push pin from insulator base at speed 25± 3 mm per minute	More than 0.8 Kgf

**9. ENVIRONMENTAL PERFORMANCE:**

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Solder ability	Tin-Lead Process: Soldering time: 5 ± 0.5 second Soldering pot: 230 ± 5°C Lead-Free Process: Soldering time: 3 ± 0.5 second Soldering pot: 245 ± 5°C	Minimum: 90% of immersed area
9.2	Resistance to soldering heat	Soldering time: 5 ± 0.5 second Soldering pot: 260 ± 5°C Tin-Lead Process for SMT Type: Refer Reflow temperature profile(11.1) Lead-Free Process for SMT Type: Refer Reflow temperature profile(11.2)	No damage
9.3	Heat aging	105± 2°C, 96 hours	No damage
9.4	Humidity	40± 2°C, 90-95% RH, 96 hours measurement must be taken within 30 min. after tested	Appearance: No damage Contact resistance: Less than twice of initial Dielectric strength: To pass para 7-3



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	ITEM	TEST CONDITION	REQUIREMENT
9.5	Temperature cycling	One cycle consists of : (1)-55 <sup>+0</sup> / <sub>-3</sub> °C , 30 min. (2)Room temp. 10-15 min. (3) 85 <sup>+3</sup> / <sub>-0</sub> °C , 30 min. (4)Room temp. 10-15 min.	Appearance: No damage Contact resistance: Less than twice of initial
9.6	Salt spray	Temperature: 35± 3°C Solution: 5± 1% Spray time: 48± 4 hours Measurement must be taken after water rinse	Appearance: No damage Contact resistance: Less than twice of initial

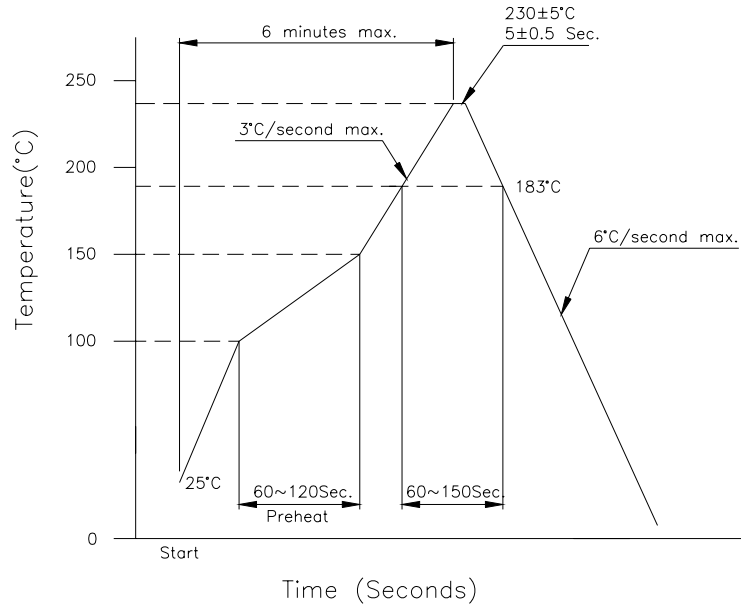
10. AMBIENT TEMPERATURE RANGE:

-40 to + 105°C ; + 215°C intermittent (Vapor Phase Solder Reflow) for SMT type

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11. Recommended IR Reflow Temperature Profile:

11.1 Using Typical Solder Paste



11.2 Using Lead-Free Solder Paste

